

Title (en)  
ELECTRONIC DEVICE, CONNECTOR, AND METHOD FOR PRODUCING ELECTRONIC DEVICE

Title (de)  
ELEKTRONISCHE VORRICHTUNG, VERBINDUNGER UND VERFAHREN ZUR HERSTELLUNG EINER ELEKTRONISCHEN VORRICHTUNG

Title (fr)  
DISPOSITIF ÉLECTRONIQUE, CONNECTEUR ET PROCÉDÉ DE PRODUCTION DE DISPOSITIF ÉLECTRONIQUE

Publication  
**EP 3588554 A1 20200101 (EN)**

Application  
**EP 17838112 A 20170220**

Priority  
JP 2017006029 W 20170220

Abstract (en)  
An electronic device has a sealing part 90, a first terminal 11 projecting outward from a first side surface of the sealing part 90, a second terminal 13 projecting outward from a second side surface different from the first side surface of the sealing part 90, an electronic element 95 provided inside the sealing part 90, and a head part 40 coupled to the first terminal 11 and the second terminal and connected to a front surface of the semiconductor element 95 via a conductive adhesive 75.

IPC 8 full level  
**H01L 23/48** (2006.01); **H01L 21/60** (2006.01)

CPC (source: EP KR US)  
**H01L 23/31** (2013.01 - KR US); **H01L 23/48** (2013.01 - EP); **H01L 23/4828** (2013.01 - KR US); **H01L 23/49513** (2013.01 - KR US); **H01L 23/49524** (2013.01 - EP); **H01L 23/49541** (2013.01 - US); **H01L 23/49551** (2013.01 - EP); **H01L 23/49562** (2013.01 - EP); **H01L 24/05** (2013.01 - US); **H01L 24/06** (2013.01 - KR); **H01L 24/16** (2013.01 - KR); **H01L 24/17** (2013.01 - KR); **H01L 24/48** (2013.01 - US); **H01L 2224/0603** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US)

C-Set (source: EP)  
**H01L 2224/48091** + **H01L 2924/00014**

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 3588554 A1 20200101**; **EP 3588554 A4 20200902**; **EP 3588554 B1 20241009**; CN 109075146 A 20181221; JP 6349470 B1 20180627; JP WO2018150558 A1 20190221; KR 102048481 B1 20191125; KR 20180105629 A 20180928; US 11404353 B2 20220802; US 2020219797 A1 20200709; WO 2018150558 A1 20180823

DOCDB simple family (application)  
**EP 17838112 A 20170220**; CN 201780003204 A 20170220; JP 2017006029 W 20170220; JP 2017555413 A 20170220; KR 20187008203 A 20170220; US 201715751845 A 20170220